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In situ x-ray diffraction study of graphitic carbon formed during heating and cooling of amorphous-C/Ni bilayers

K. L. Saenger, a) J. C. Tsang, A. A. Bol, J. O. Chu, A. Grill, and C. Lavoie
IBM Semiconductor Research and Development Center Research Division, T. J. Watson Research Center, Yorktown Heights, New York 10598, USA
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We examine graphitization of amorphous carbon (a-C) in a-C/Ni bilayer samples having the structure Si/SiO2/a-C/(3–30 nm)/Ni(100 nm). In situ x-ray diffraction (XRD) measurements during heating in He at 3 °C/s to 1000 °C showed graphitic C formation beginning at temperatures T of 640–730 °C, suggesting graphitization by direct metal-induced crystallization, rather than by a dissolution/precipitation mechanism in which C is dissolved during heating and expelled from solution upon cooling. We also find that graphitic C, once formed, can be reversibly dissolved by heating to T>950 °C, and that nongraphitic C can be volatilized by annealing in H2-containing ambients. © 2010 American Institute of Physics. [doi:10.1063/1.3397985]

Few-layer graphene has attracted intense interest as a possible material for post-silicon electronic devices due to its high mobility, two-dimensional structure, and tunable band gap.1–3 Methods for forming graphene such as mechanical exfoliation from graphite and decomposition of single-crystal SiC (Ref. 4) are not readily scalable to the wafer-scale dimensions that are expected to be required for semiconductor manufacturing. One potentially scalable method is metal-catalyzed chemical vapor deposition (CVD), in which graphene is formed on a metallic template layer exposed to a carbon-containing gas at elevated temperature (900–1000 °C). Several groups have shown that it is possible to grow few-layer graphene on Ni and transfer it to insulating substrate layers.2,5,6

We have been investigating alternative metal-catalyzed graphene formation processes utilizing solid phase sources of carbon. In this approach, the carbon is not introduced from the gas phase but rather as one of the layers in an amorphous carbon (a-C)/Ni bilayer stack. It was hoped that this approach would provide films of quality comparable to those achieved by CVD but with better control over film thickness (since the carbon supply is fixed and finite). Our own results and those of Zheng et al.7 indicate that continuous films of few-layer graphene may be produced with this approach under certain optimized conditions.

The present work focuses on the kinetics and mechanism of multilayer graphene formation in a-C/Ni bilayer structures comprising a top layer of Ni over bottom layer of a-C disposed on a thermally oxidized Si substrate. Our initial expectation was that graphene would form by a simple dissolution/precipitation mechanism in which C from the a-C layer would dissolve into the Ni layer during heating and be expelled from solution upon cooling below the solid solubility limit, the mechanism previously seen with graphene growth by CVD.2,3,6 However, the appearance of a surface layer of graphitic carbon after annealing at temperatures at which the C solubility in Ni is still very low (550–750 °C) suggested that a metal-induced crystallization and layer exchange mechanism analogous to that seen with Al-induced crystallization of amorphous Si (a-Si) (Refs. 8–10) might be more likely. In this scenario, the C in Ni has a low concentration and a high transport rate. Nucleation sites for graphite (typically metal grain boundaries) provide a sink for the dissolved carbon which is replenished by continued dissolution of the a-C layer. For both the a-Si/Al and a-C/Ni cases, the driving force for crystallization is thermodynamic stability of the crystalline C or Si phase relative to the amorphous phase.

Distinguishing between these two graphitization mechanisms can be difficult without a means of determining exactly when during the thermal treatment the graphitic carbon appears. For a simple dissolution/precipitation mechanism, graphitic carbon would be expected to appear only during the cooling part of the heat treatment. For a metal-induced crystallization mechanism, graphitic carbon would be expected to appear merely after a sufficient amount of time at a sufficiently elevated temperature. In the experimental approach used here (one previously used to study metal-induced crystallization of a-Si (Ref. 11) and a-Ge (Ref. 12) as well as carbide formation13 in a-C/metal bilayers), in situ x-ray diffraction (XRD) during annealing was used to detect the formation graphitic carbon, which has a strong 002 reflection corresponding to a d-spacing of 0.34 nm.

Thermally oxidized substrates (SiO2 thickness ~300 nm) were in situ sputter precleared and then sequentially coated with a-C and Ni by sputter deposition from C and Ni targets in ~10 mTorr Ar. The resulting a-C/Ni bilayer samples had a-C thicknesses of 3, 10, and 30 nm and a Ni thickness of 100 nm.

In situ XRD measurements during annealing (heating and cooling at 3 °C/s to and from 1000 °C in He or N2/H2(5%)) were performed at the National Synchrotron Light Source of the Brookhaven National Laboratory (IBM/MIT beamline X-20C) with synchrotron radiation having a wavelength of 0.1797 nm, intensity of 1013 photons/s, and energy resolution of 1.5%.14 Additional ex situ θ–2θ XRD scans were also performed at room temperature over a wider 2θ range in a Bragg–Brentano geometry with Cu Kα radiation (λ=0.1542 nm) after rapid thermal anneals (RTAs) with 35 °C/s heating rates to 900–1000 °C in N2 or Ar/H2(5%), as well as after furnace anneals in N2/H2(5%) at 550 °C. Raman spectroscopy

a)Electronic mail: saenger@us.ibm.com.
indicated that the graphitic carbon formed was present as a top surface layer.

Figure 1 shows \textit{ex situ} XRD data for a-C(30 nm)/Ni(100 nm) samples before and after interfacial crystallization. In N\textsubscript{2} or Ar/H\textsubscript{2}, the peak intensities are stronger for the a-C(30 nm) samples, about a factor of 10 lower for the a-C(10 nm) samples, and almost below the detection limit for the a-C samples, about a factor of 10 lower for the a-C samples. As shown in Fig. 2 for the cases of 1000 °C/10 s RTA annealing in N\textsubscript{2} or Ar/H\textsubscript{2}, the peak intensities are strongest for the a-C(30 nm) samples, due to a factor of 10 lower for the a-C(10 nm) samples, and almost below the detection limit for the a-C(3 nm) samples. Similar results were seen for 950 °C RTA annealing in N\textsubscript{2} or Ar/H\textsubscript{2}; 3 nm a-C samples showed more variability, with some showing no detectable graphite XRD intensity at all.

The intensities and line shapes of the 002 graphite peak vary with the initial a-C layer thickness. As shown in Fig. 2, the implied crystallite sizes (computed from $\lambda/\cos(\theta_B) - \Delta(2\theta_B)$) with the Bragg angle $\theta_B$ in radians\textsuperscript{15} are 13 nm and 32 nm, respectively, in good agreement with the initial a-C thicknesses of 10 and 30 nm.

Figure 3(a) shows a contour map of \textit{in situ} XRD data between 500 and 800 °C for a a-C(3 nm)/Ni sample heated from room temperature to 1000 °C at 3 °C/s in He and Fig. 3(b) compares the integrated graphite intensity data for this sample with that of two other having thicker (10 and 30 nm) initial a-C layers. The graphite peak in Fig. 3(a) appears at 2\theta~30.5° during heating, lending support to a metal-induced crystallization model. Graphite formation appears to be abrupt, with “widths” of formation (defined as the difference between the minimum and maximum in the second derivative of graphite peak intensity) of about 20–30 °C. Thinner a-C layers were observed to have both an earlier mean temperature of graphite formation (defined as the temperature at which the first derivative of the graphite peak intensity is a maximum), with values of ~640 °C for 3 nm, 680 °C for 10 nm, and 730 °C for 30 nm, as well as an earlier \textit{onset} of graphite formation. The latter result was counterintuitive in that we expected the onset temperature to be independent of a-C layer thickness. We speculate that these differences may be due to interface energy effects or to the influence of interfacial or incorporated C on the time evolution of the Ni grain structure. For example, very thin a-C layers may be inherently more unstable, or some rate-limiting diffusion process necessary for Ni grain growth may be faster at SiO\textsubscript{2}/Ni interfaces which might form (at least in localized regions) at an earlier stage of heating with thinner (and more easily consumed) a-C layers. However, it should be noted that the 3 nm a-C samples showed more variability, with some showing no detectable graphite XRD intensity at all.

FIG. 1. (Color online) \textit{Ex situ} XRD scans of Si/SiO\textsubscript{2}/a-C(30 nm)/Ni(100 nm) samples before (a) and after RTA annealing at 900 °C for 1 min in (b) N\textsubscript{2} and (c) Ar/H\textsubscript{2}. Note the log scale and arbitrary baseline offsets.

FIG. 2. (Color online) \textit{Ex situ} XRD scans over the 002 graphite peak of Si/SiO\textsubscript{2}/a-C/Ni(100 nm) samples with different thicknesses of a-C, after RTA annealing at 1000 °C for 10 s in ambient of N\textsubscript{2} or Ar/H\textsubscript{2}: 3 nm a-C in (a) N\textsubscript{2} or (b) Ar/H\textsubscript{2}; 10 nm a-C in (c) N\textsubscript{2} or (d) Ar/H\textsubscript{2}; and 30 nm a-C in (e) N\textsubscript{2} or (f) Ar/H\textsubscript{2}. The intensity scale is linear.

FIG. 3. \textit{In situ} XRD results. (a) The 002 graphite peak in a Si/SiO\textsubscript{2}/a-C(3 nm)/Ni(100 nm) sample heated in He at a ramp rate of 3 °C/s. (b) Graphite peak intensity data (integrated over the 2\theta range 29.5° to 31.5°) for the same sample (line) compared to corresponding data for samples with initial a-C thicknesses of 10 nm (dashed) and 30 nm (dashed-dotted). The contour lines in (a) have a linear intensity spacing.
formation of volatile hydrocarbons produced by carbon +hydrogen reactions when ramp rates are slow (3 °C/s), an explanation that is supported by additional ex situ XRD measurements. For 30 nm a-C samples, we found that 550 °C/2 h furnace annealing in N₂/H₂ produced no graphite signal, whereas the same anneal in N₂ produced graphite intensities about a third of those found for RTA anneals of a fresh sample at 900–1000 °C. In addition, RTA treatments of 900 °C/1 min in N₂ produced no graphite in samples previously given the N₂/H₂ 550 °C/2 h anneal. It was also found that 550 °C/2 h anneals in N₂/H₂ performed subsequent to formation of graphitic carbon by 900 °C/1 min N₂ annealing had no effect on the graphite peak intensity, supporting the notion that the C removed by the H₂ is amorphous rather than graphitic.

In summary, we have used in situ XRD during annealing to examine the formation of graphitic carbon from a-C/Ni bilayers. It was found that a simple dissolution/precipitation mechanism cannot account for our observation that graphitic carbon is first formed during heating rather than cooling. While a dissolution/precipitation mechanism is present, it is seen only after graphitic carbon has already formed; the initial formation mechanism appears to be a metal-induced crystallization and layer exchange mechanism analogous to that seen with Al-induced crystallization of a-Si. It was also observed that low temperature annealing in H₂-containing ambients can volatilize nongraphitic carbon.

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![FIG. 4. Contour maps of in situ XRD results showing the 002 graphite peak in Si/SiO₂/a-C/Ni(100 nm) samples heated to and cooled from 1000 °C in He at a ramp rate of 3 °C/s for a-C thicknesses of (a) 3 nm, (b) 10 nm, and (c) 30 nm. The contour lines have a linear intensity spacing that is different for each a-C thickness.](image)